



## UNITED STATES PATENT AND TRADEMARK OFFICE

UNITED STATES DEPARTMENT OF COMMERCE  
 United States Patent and Trademark Office  
 Address: COMMISSIONER FOR PATENTS  
 P.O. Box 1450  
 Alexandria, Virginia 22313-1450  
 www.uspto.gov

**\*BIBDATASHEET\***

Bib Data Sheet

**CONFIRMATION NO. 3651**

SERIAL NUMBER 10/693,952	FILING DATE 10/28/2003  RULE	CLASS 156	GROUP ART UNIT 1763	ATTORNEY DOCKET NO. 8017-1104
-----------------------------	---------------------------------------	--------------	------------------------	-------------------------------------

APPLICANTS

Noriyuki Sakuma, Tokyo, JAPAN;  
 Kinji Tsunenari, Tokyo, JAPAN;

\*\* CONTINUING DATA \*\*\*\*\*  
*nae fm*

\*\* FOREIGN APPLICATIONS \*\*\*\*\*  
 JAPAN 2002-312542 10/28/2002  
*fm*

IF REQUIRED, FOREIGN FILING LICENSE GRANTED  
 \*\* 02/06/2004

Foreign Priority claimed 35 USC 119 (a-d) conditions met	<input checked="" type="checkbox"/> yes <input type="checkbox"/> no <input checked="" type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> Met after Allowance <i>nae fm</i> Examiner's Signature Initials	STATE OR COUNTRY JAPAN	SHEETS DRAWING 4	TOTAL CLAIMS 17	INDEPENDENT CLAIMS 2
---	---	------------------------------	------------------------	-----------------------	----------------------------

ADDRESS  
 000466  
 YOUNG & THOMPSON  
 745 SOUTH 23RD STREET 2ND FLOOR  
 ARLINGTON , VA  
 22202

TITLE  
 Wafer polishing method and wafer polishing apparatus in semiconductor fabrication equipment

FILING FEE  RECEIVED	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT No. _____ for following:	<input type="checkbox"/> All Fees
		<input type="checkbox"/> 1.16 Fees ( Filing )
		<input type="checkbox"/> 1.17 Fees ( Processing Ext. of time )
		<input type="checkbox"/> 1.18 Fees ( Issue )